

Amendments to the Abstract

Please replace the abstract with the new abstract as follows:

--A solder bump structure for use on a substrate. The solder bump structure includes a multilayer underbump metallization having a major upper surface with a solder wettable caplayer for contacting a solder bump, the multilayer underbump metallization projecting from said substrate with an exposed sidewall; a thin layer of a metal selected from a group consisting of titanium, chrome, a titanium-nickel-titanium composite, a titanium-nickel-chrome composite, a titanium-platinum-titanium alloy, and a titanium-nickel-oxidized silicon composite deposited over or under said multilayer underbump metallization and covering the exposed sidewall of said multilayer underbump metallization.--